

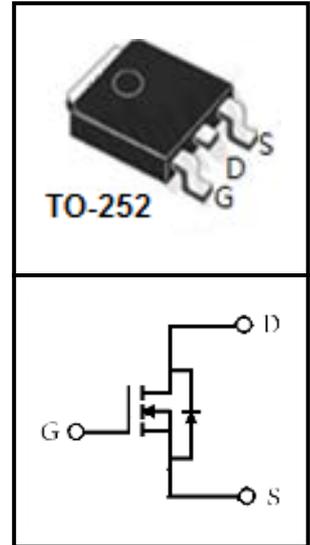
30V N-Channel Trench MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits



Device Marking and Package Information		
Device	Package	Marking
CTD03N4P3	TO-252	CTD03N4P3

Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	30	V
Drain Current-Continuous($T_c = 25^\circ\text{C}$)	I_D	105	A
Drain Current-Continuous($T_c = 100^\circ\text{C}$)		75	
Pulsed Drain Current	I_{DM}	370	A
Gate Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy	E_{AS}	300	mJ
Power Dissipation $T_c = 25^\circ\text{C}$	P_D	85	W
Power Dissipation $T_c = 100^\circ\text{C}$		40	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+175	$^\circ\text{C}$

Thermal Characteristics			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note1)	$R_{\theta jc}$	1.85	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	uA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V, T_J = 55^\circ\text{C}$	--	--	5	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.5	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	--	3.2	4.3	m Ω
		$V_{GS} = 4.5V, I_D = 20A$	--	5.3	7.0	m Ω
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 15V,$ $f = 1.0\text{MHz}$	--	2150	--	pF
Output Capacitance	C_{oss}		--	328	--	
Reverse Transfer Capacitance	C_{rss}		--	281	--	
Total Gate Charge (4.5V)	Q_g	$V_{DS} = 25V, I_D = 30A,$ $V_{GS} = 10V$	--	39.8	--	nC
Gate-Source Charge	Q_{gs}		--	3.2	--	
Gate-Drain Charge	Q_{gd}		--	13.5	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 15V, R_L = 0.75\Omega$ $V_{GS} = 10V, R_G = 3\Omega$	--	22.8	--	ns
Turn-on Rise Time	t_r		--	33.5	--	
Turn-off Delay Time	$t_{d(off)}$		--	56	--	
Turn-off Fall Time	t_f		--	32.6	--	
Body Diode Characteristics						
Continuous Body Diode Current	I_{SD}	$T_C = 25^\circ\text{C}$	--	--	105	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 20A, V_{GS} = 0V$	--	--	1.2	V
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 30A,$ $di/dt = 100A/\mu s$	--	14.3	--	nS
Reverse Recovery Charge	Q_{rr}		--	4.1	--	NC

Notes

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.5mH$
4. The power dissipation is limited by 175°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

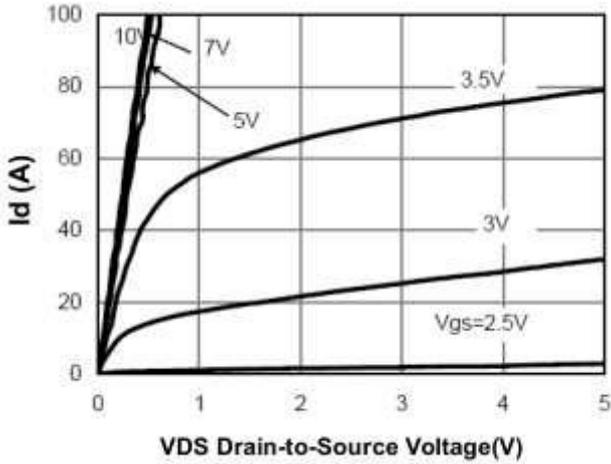


Fig.1 Typical Output Characteristics

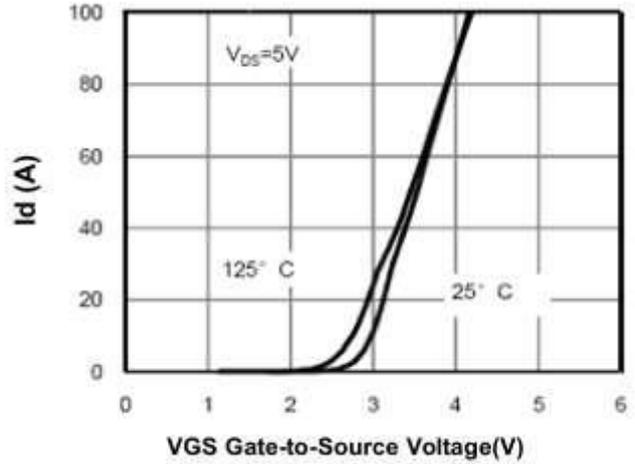


Fig.2 On-Resistance vs. G-S Voltage

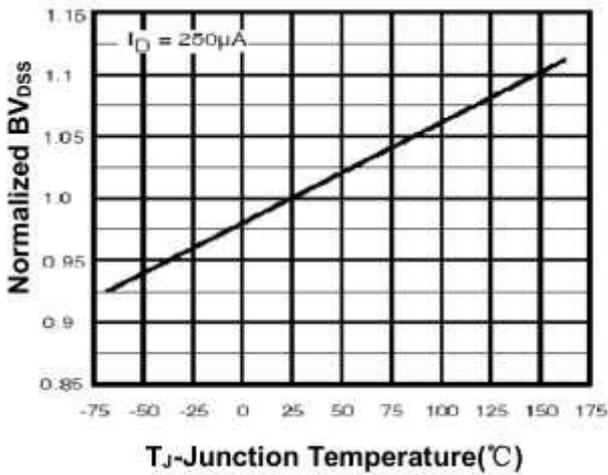


Fig.3 Source Drain Forward Characteristics

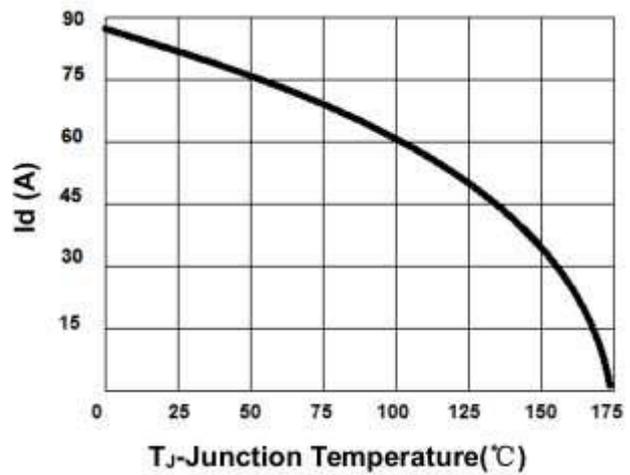


Fig.4 Gate-Charge Characteristics

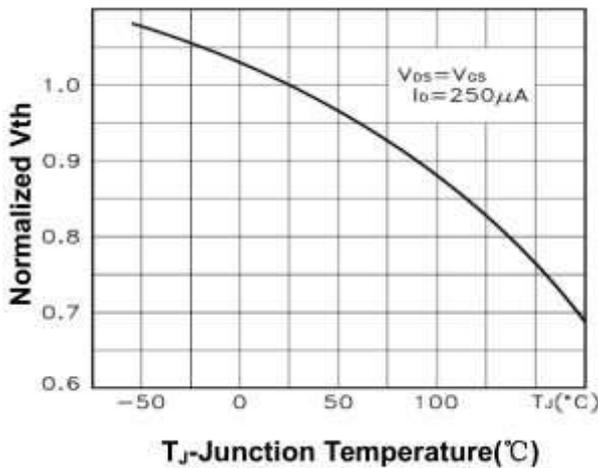


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

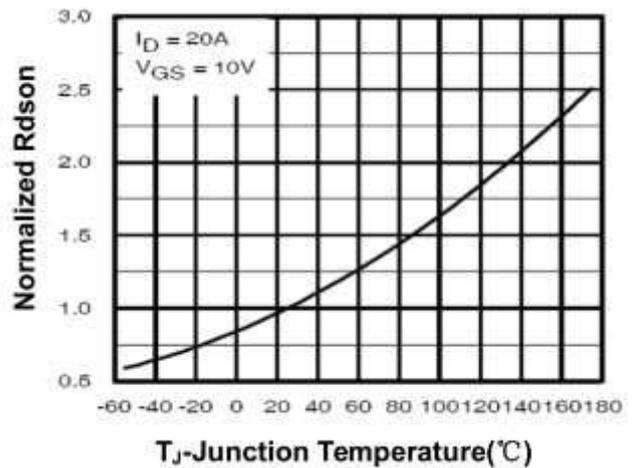


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

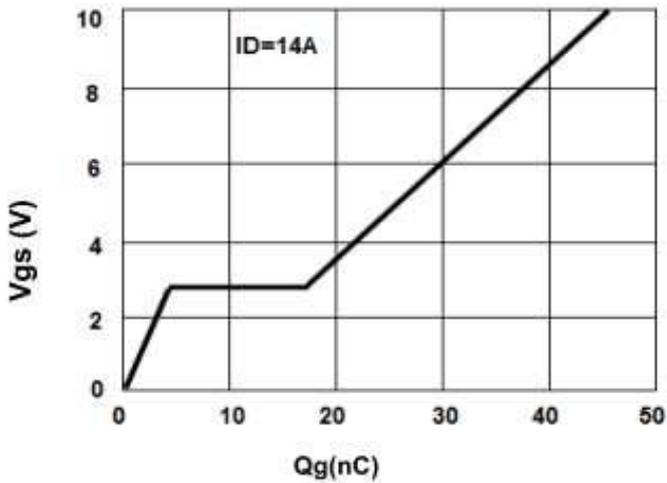
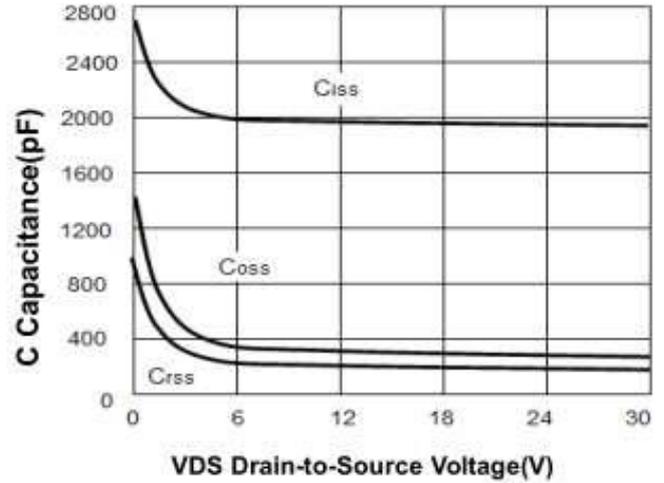
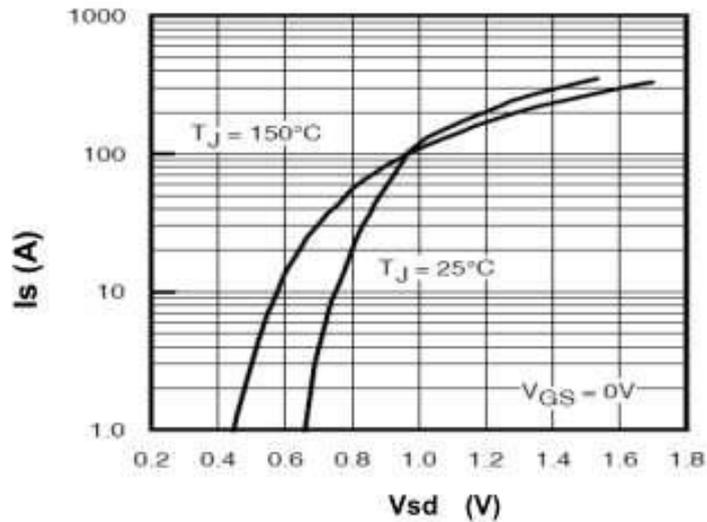
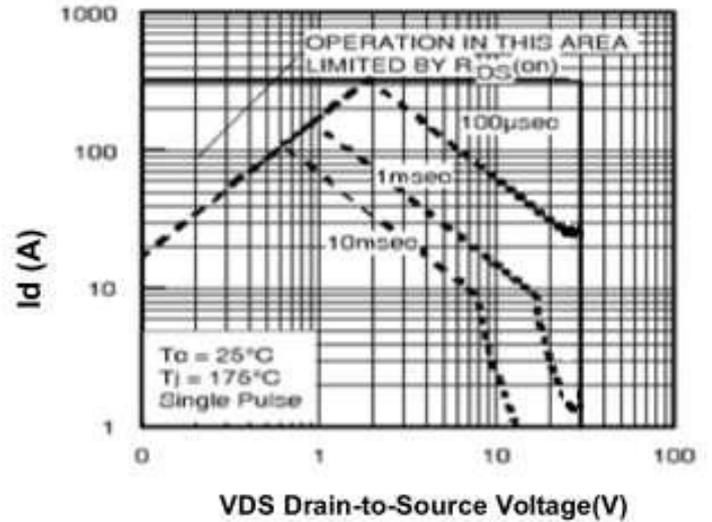
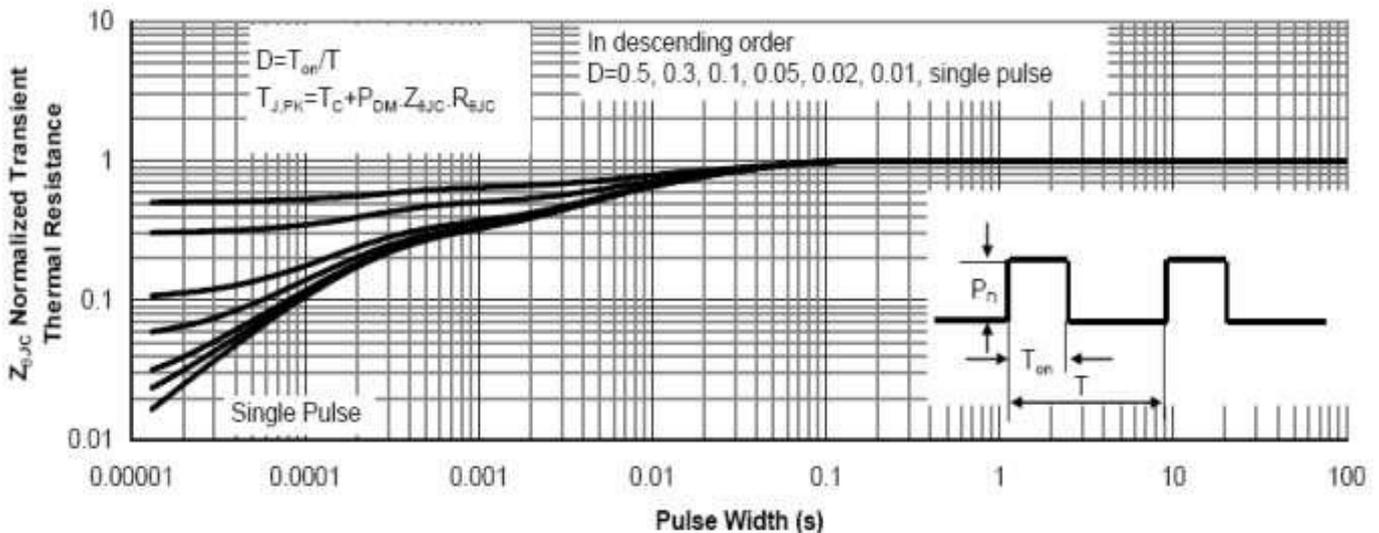
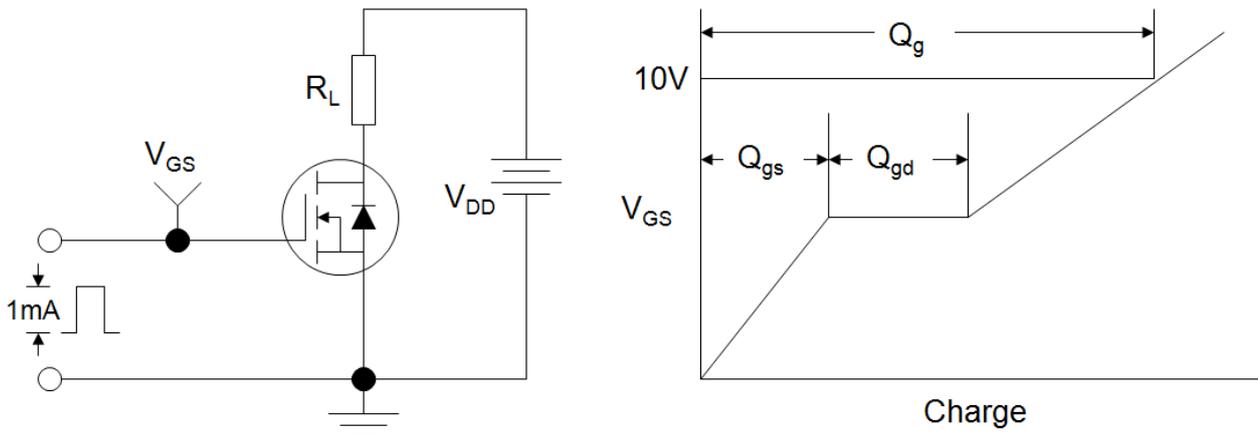
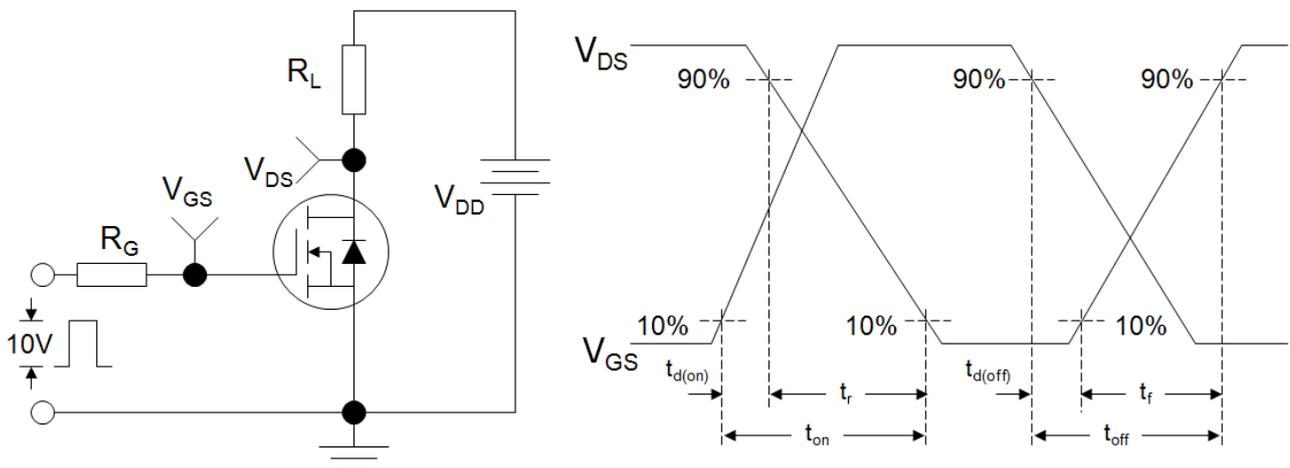
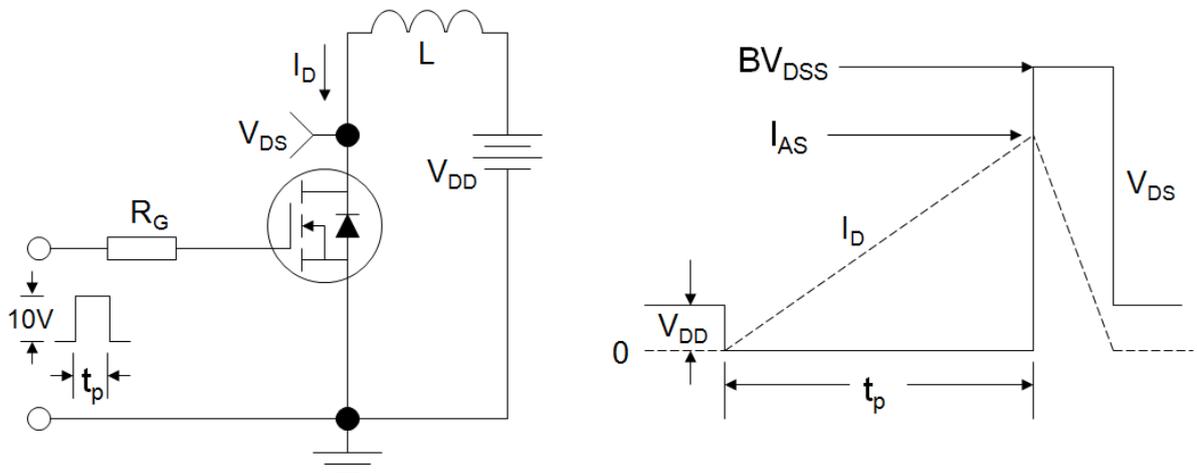
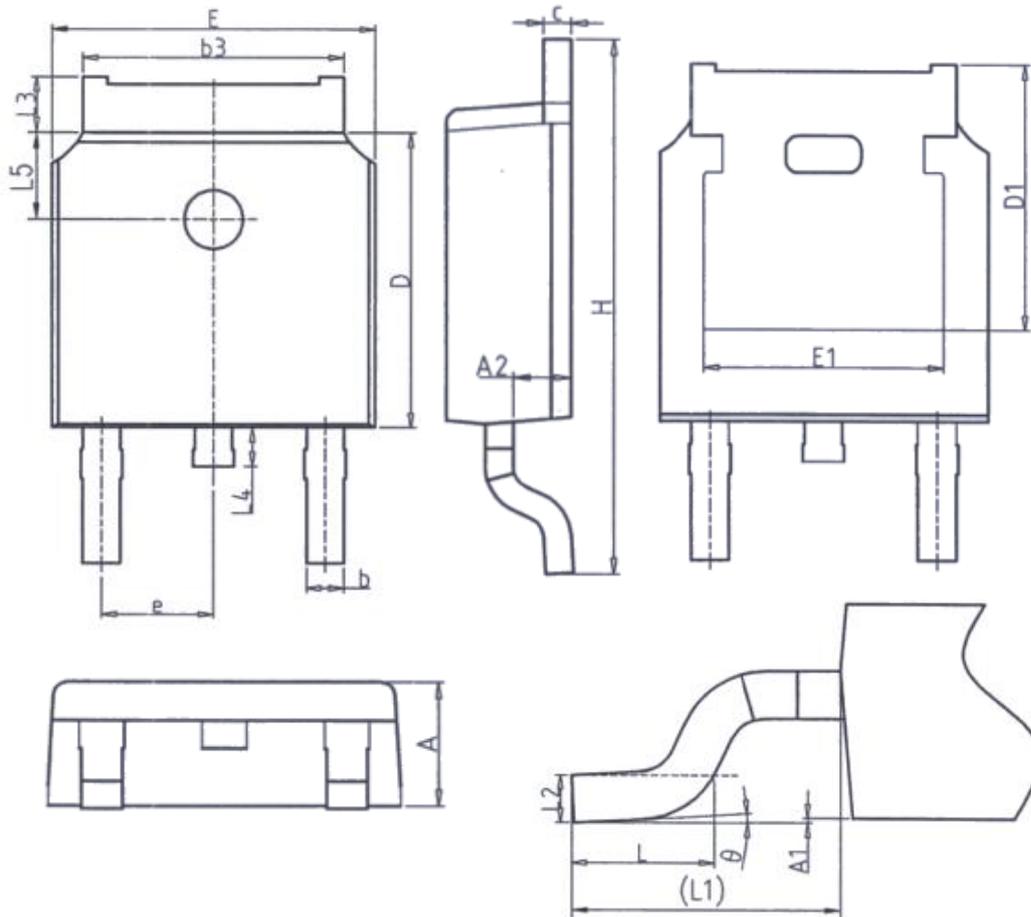
Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Gate Charge Waveforms

Figure 8. Capacitance

Figure 9: Body-Diode Characteristics

Figure 10: Maximum Safe Operating Area

Figure.11: Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


TO-252


Unit: mm		
Symbol	Min.	Max.
A	2.20	2.40
A1	0.00	0.20
A2	0.97	1.17
b	0.68	0.90
b3	5.20	5.50
c	0.43	0.63
D	5.98	6.22
D1	5.30REF	
E	6.40	6.80
E1	4.63	-

Unit: mm		
Symbol	Min.	Max.
e	2.286BSC	
H	9.40	10.50
L	1.38	1.75
L1	2.90REF	
L2	0.51BSC	
L3	0.88	1.28
L4	-	1.00
L5	1.65	1.95
θ	0°	8°

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